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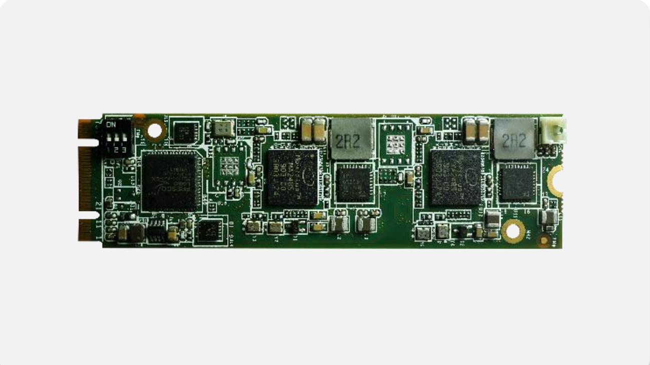
EGPA-I201

M.2 2280 to Dual Intel Movidius Myriad X AI module

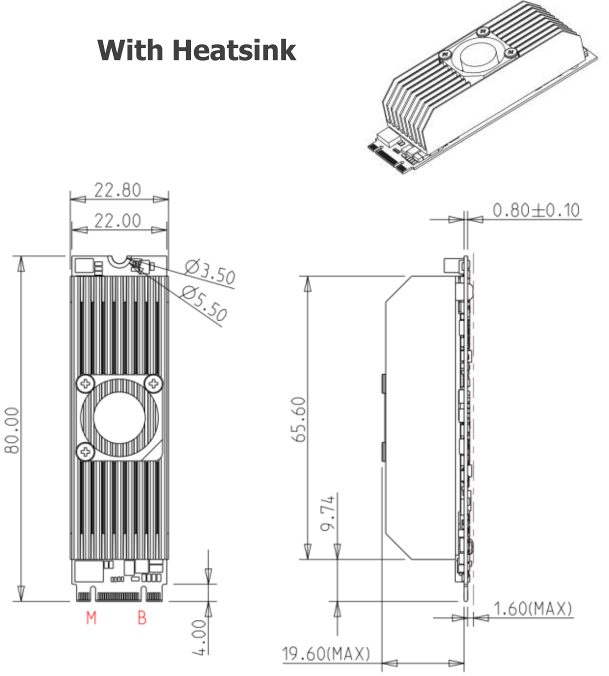


Features

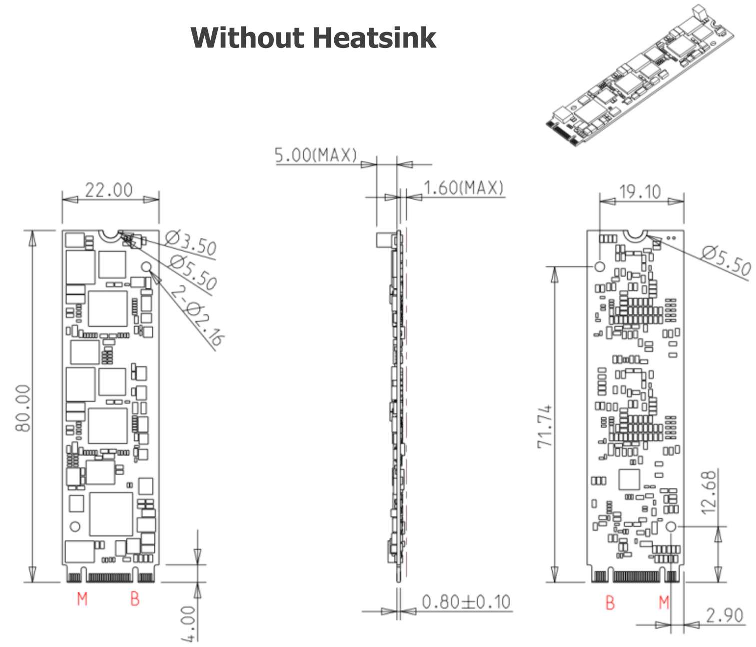
- M.2 2280 B+M Key to 2 Movidius Myriad X
- Low Power Design
- Support Intel OpenVINO Toolkit
- Supported Framework: TensorFlow, Caffe, MXNET
- Complies with CE/FCC Class A
- 30μ” golden finger, 3-year warranty

Mechanical Drawing

With Heatsink



Without Heatsink



Specifications

Form-Factor	M.2 2280 B+M Key
Input I/F	PCI Express 2.0 x 1
TDP	8W
Dimension (WxLxH)	With Heatsink: 22.8 x 80.0 x 22 mm, Weight: 34.12g Without Heatsink: 22.0 x 80.0 x 7.4 mm, Weight: 6.89g
Temperature	Operation: 0°C ~ +60°C
Support Framework	TensorFlow, Caffe, MXNET
OS Support	Windows 10 64-bit Ubuntu 18.04, 64-bit
Notes	Please download OpenVINO Toolkit from Intel website: https://docs.openvinotoolkit.org/latest/index.html

Order information

EGPA-I201-C1
mPCIe to Two Intel Movidius Myriad X AI module, with Heatsink

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